



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Winter Meetings 2026

Wednesday, March 4, 2026

SEMI Japan Office Room 1 / OVTCCM (Hybrid)

9:00am – 12:00pm JST

TC Chapter Announcements

Next TC Chapter Meeting

9:00am – 12:00pm (JST), May 21, 2026 @ SEMI Japan office and OVTCCM (Hybrid)

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Tsuyoshi Nagashima (Miraial), Daisuke Sado (EAGLE INDUSTRY), Yasuhisa Ito (Murata Machinery)

SEMI Staff: Takeaki Hirabara

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Acteon NEXT	Komatsu	Shoji	JEOL	Asayama	Kyoichiro
<i>Miraial</i>	<i>Nagashima</i>	<i>Tsuyoshi</i>	<i>Marubeni Plax Corporation</i>	<i>Igeta</i>	<i>Luke</i>
EAGLE INDUSTRY	Sado	Daisuke	TDK	Okabe	Tsutomu
Murata Machinery	Ito	Yasuhisa	DAIFUKU	Suzuki	Tomoko
DAIHEN	Kishi	Daisuke	DAIFUKU	Nishizawa	Naoyuki
KOKUSAI ELECTRIC	Matsuda	Mitsuhiro	SCREEN Semiconductor Solutions	Nishimura	Takayuki
Hirata Corporation	Kanazawa	Keiji	SCREEN Semiconductor Solutions	Futatsugi	Tetsuya
SINFONIA TECHNOLOGY	Matsukubo	Taisuke	GENETEC	<i>Tsunobuchi</i>	<i>Hirokazu</i>
<i>Shin-Etsu Polymer</i>	<i>Odashima</i>	<i>Satoshi</i>	AOI ELECTRONICS	<i>Iwabu</i>	<i>Koji</i>
Shin-Etsu Polymer	Kawase	Hiroyuki	DISCO	<i>Gonsui</i>	<i>Shinobu</i>
Shin-Etsu Polymer	Imai	Masako	CKplas	<i>Chen</i>	<i>Tiffany</i>
<i>Intel</i>	<i>Radloff</i>	<i>Stefan</i>	CKplas	<i>Ng</i>	<i>Angie</i>
<i>Intel</i>	<i>Raman</i>	<i>Kartik</i>	CKplas	<i>Chen</i>	<i>Candy</i>
<i>Intel</i>	<i>Slinker</i>	<i>Danniel</i>	DNJO Technologies	<i>Su</i>	<i>Vera</i>
TDK	Kanashiro	Kiyoshi			
ASE	Mulder	Shen	SEMI HQ	BK	Lok
ASE	Ping Feng	Yang	SEMI Japan	Yoshida	Akiko
CKplas	Ng	Angie	SEMI Japan	Koga	Nahoko
<i>Peer Group</i>	<i>Fuchigami</i>	<i>Albert</i>	SEMI Japan	Hirabara	Takeaki



Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
7332	New Standard: Specification for Large JEDEC™ Tray Stack Load Port	Passed with Technical Changes

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&R Action</i>	<i>A&R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
7455	SNARF	Next Gen Assembly / Test Material Handling TF	Line Item Revision to Doc#7374: Specification for Panel FOUP load port with ground based delivery exclusion volume
7453	SNARF	310mm Square Panel FOUP Task Force	New Standard: Specification for 310mm Square Panel FOUP
7454	SNARF	Global PIC Maintenance Task Force	Line Item Revision to E100-1104 (Reapproved 0710): Specification for a Reticle SMIF Pod (RSP) Used to Transport and Store 6 Inch or 230 mm Reticles
	PCR	Next Gen Assembly / Test Material Handling TF	Figure Change (Figure 21 and 23) - SEMI E197-0226 (Preliminary) SPECIFICATION FOR LARGE TRAY STACK FOUP (LTSF) *Editorial Change Type 2

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

Table 8 Authorized Ballots

#	When	TF	Details
7453	Cycle 5, 2026	310mm Square Panel FOUP Task Force	New Standard: Specification for 310mm Square Panel FOUP
7454	Cycle 3, 2026	Global PIC Maintenance Task Force	Line Item Revision to E100-1104 (Reapproved 0710): Specification for a Reticle SMIF Pod (RSP) Used to Transport and Store 6 Inch or 230 mm Reticles

Table 9 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 10 SNARF(s) Cancelled

#	TF	Title
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
PIC_20260304_1	SEMI Staff	Check whether the discount code issued by SEMI HQ for SEMI U is effective Japanese course too or not.

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
PIC_20251218_1	SEMI Staff	Report and request an action for E100 modification to have to NA PIC→Close. *Will be balloted on Cycle 3, 2026.

1 Welcome, Reminders, and Introductions

Yasuhisa Ito called the meeting to order at 9:00am JST. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 1. Required_Meeting_Element Dec 2024_JPupdated

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.



Motion: Approve the minutes as written
By / 2nd: Shoji Komatsu (Acteon NEXT LLC) / Daisuke Sado (EAGLE INDUSTRY CO., LTD)
Discussion: None
Vote: 14-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority
Attachment: 2. 20251218 Japan PIC Committee Minutes_rev1

3 Liaison Reports

3.1 *Physical Interfaces & Carriers North America TC Chapter*

Takeaki Hirabara (SEMI Staff) reported for the Physical Interfaces & Carriers *North America* TC Chapter. Of note:

- Last Meeting: Wednesday, February 11, 2026 / Full Virtual | NA Winter meetings via OVTCCM
- Next Meeting: Wednesday, May 13, 2026 / NA Spring Meetings in conjunction with SEMI ASMC (Advanced Semiconductor Manufacturing Conference) at Hilton Albany in Albany, New York.
- Doc#6832 from Electron Microscopy Workflow TF granted One-Year Extension until winter 2027.

Attachment: 3. NA PIC Liaison Report Feb2026 v1

3.2 *JRSC*

There are no matters to report since JRSC meeting has not been held from previous PIC meeting.

4 SEMI Staff Report

Takeaki Hirabara (SEMI Staff) gave the SEMI Staff Report. Of note:

- Sharing 2026 calendar of SEMICON events until September.
- Report of Facts and Figures of SEMICON Japan 2025.
- It has been occurred issue on SVM platform access from China, and the platform is under rebuilding to address the issue.

Attachment: 4. Staff_HQ Report Feb 2026_JA_R1

5 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

5.1 Document # 7332, New Standard: Specification for Large JEDEC™ Tray Stack Load Port → Passed with Technical Changes

Attachment: 5. A&R_7332

6 Subcommittee and Task Force Reports

6.1 Global PIC Standards Maintenance TF

Shoji Komatsu (Acteon NEXT) reported the Global PIC Standards Maintenance TF. Of note:

- Explained the correction of the error in Figure 8 of 100.
 - *The SANRF and ballot authorization refer to the New Business part.

Attachment: 6. 260304_GlobalPICTF_JP

6.2 Japan Electron Microscopy Workflow Liaison TF

Takeaki Hirabara (SEMI) reported for the Japan Electron Microscopy Workflow Liaison Task Force. Of note:

- Sharing Plan and Progress of LCC Prototyping.
 - ◆ Prototype and evaluate using machined resin parts (Until March 2026) is now on going.

Attachment: 7. 260304_PI&C TC JP

6.3 Panel Level Packaging Panel FOUP TF

Shoji Komatsu (Acteon NEXT) reported the Panel Level Packaging Panel FOUP TF. Of note:

- TF requested a SNARF for Line Item of Doc#7374: Specification for Panel FOUP load port with ground based delivery exclusion volume before publishing. *Refer to the New Business

Attachment: 8. 260304_PLPTF_JP

6.4 Next Gen Assembly / Test Material Handling TF

Stefan Radloff (Intel) reported the Next Gen Assembly / Test Material Handling TF based of a slide including in the Liaison Report of NA TC Chapter. Of note:

- Pending Publications
- E84 TCPIP Subteam activities
- *Refer to the NA TC Chapter Liaison Report in attachments.
- Explanation of update for E197 new published standard. PCR approval: refer to the New Business

Attachment: 9. NGAT LTSF E197 updates

6.5 310mm Square Panel FOUP TF

Shoji Komatsu (Acteon NEXT) reported the 310mm Square Panel FOUP TF. Of note:

- SNARF approval request due to scope change from 7405. Refer to the New Business.

Attachment: 10. 260304_310mm_JP

6.6 [Liaison: 3D Packaging & Integration JA TCC] Panel Level Packaging Glass Carrier TF: Disbanded

6.7 [Liaison: 3D Packaging & Integration NA TCC] Panel Level Packaging Panel TF

Shoji Komatsu (Acteon NEXT) shared potential of standards development related to this TF verbally.



7 Old Business

7.1 *Project Period Review* - None

7.2 *5 Year Review* - None

8 New Business

8.1 *SNARF Approval*

8.1.1 Line Item Revision to Doc#7374: Specification for Panel FOUP load port with ground based delivery exclusion volume

Motion: Approve the SNARF for Line Item Revision to Doc#7374: Specification for Panel FOUP load port with ground based delivery exclusion volume

By / 2nd: Shoji Komatsu (Acteon NEXT LLC) / Stefan Radloff (Intel)

Discussion: None

Vote: 16-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

8.1.2 New Standard: Specification for 310mm Square Panel FOUP

Motion: Approve the SNARF for New Standard: Specification for 310mm Square Panel FOUP

By / 2nd: Shoji Komatsu (Acteon NEXT LLC) / Mitsuhiro Matsuda (KOKUSAI ELECTRIC CORPORATION)

Discussion: None

Vote: 17-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

8.1.3 Line Item Revision to E100-1104 (Reapproved 0710): Specification for a Reticle SMIF Pod (RSP) Used to Transport and Store 6 Inch or 230 mm Reticles

Motion: Approve the SNARF for Line Item Revision to E100-1104 (Reapproved 0710): Specification for a Reticle SMIF Pod (RSP) Used to Transport and Store 6 Inch or 230 mm Reticles

By / 2nd: Shoji Komatsu (Acteon NEXT LLC) / Daisuke Sado (EAGLE INDUSTRY CO., LTD)

Discussion: None

Vote: 14-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

8.2 *Letter Ballot Approval*

8.2.1 New Standard: Specification for 310mm Square Panel FOUP

Motion: Authorize the Document for Letter Ballot Cycle 5, 2026: New Standard: Specification for 310mm Square Panel FOUP

By / 2nd: Shoji Komatsu (Acteon NEXT LLC) / Daisuke Sado (EAGLE INDUSTRY CO., LTD)

Discussion: None

Vote: 16-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

8.2.2 Line Item Revision to E100-1104 (Reapproved 0710): Specification for a Reticle SMIF Pod (RSP) Used to Transport and Store 6 Inch or 230 mm Reticles

Motion: Authorize the Document for Letter Ballot Cycle 3, 2026: Line Item Revision to E100-1104 (Reapproved 0710): Specification for a Reticle SMIF Pod (RSP) Used to Transport and Store 6 Inch or 230 mm Reticles

By / 2nd: Shoji Komatsu (Acteon NEXT LLC) / Daisuke Sado (EAGLE INDUSTRY CO., LTD)

Discussion: None



Vote: 14-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

8.3 PCR

8.3.1 Figure Change (Figure 21 and 23) - SEMI E197-0226 (Preliminary) SPECIFICATION FOR LARGE TRAY STACK FOUNDRY (LTSF)

Attachment: 11 A&R_PCR_E197

9 Next Meeting and Adjournment

The next meeting is scheduled at 9:00am – 12:00pm (JST), May 21, 2026 @ SEMI Japan office and OVTCCM (Hybrid). See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 11:40am JST

Respectfully submitted by:

Takeaki Hirabara

Standards & EHS

SEMI Japan

Email: thirabara@semi.org

Minutes tentatively approved by:

Tsuyoshi Nagashima (Miraial)	March 24, 2026
Daisuke Sado (EAGLE INDUSTRY)	March 24, 2026
Yasuhisa Ito (Murata Machinery)	March 24, 2026

Table 14 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
1. Required_Meeting_Element Dec 2024_JPupdated	2. 20251218 Japan PIC Committee Minutes_rev1
3. NA PIC Liaison Report Feb2026 v1	4. Staff_HQ Report Feb 2026_JA_R1
5. A&R_7332	6. 260304_GlobalPICTF_JP
7. 260304_EMW_JP	8. 260304_PLPTF_JP
9. NGAT LTSF E197 updates	10. 260304_310mm_JP
11. A&R_PCR_E197	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Takeaki Hirabara at the contact information above.